

ABSTRACT OF THE DISCLOSURE

A semiconductor device is disclosed which comprises a plurality of semiconductor chips having a plurality of terminals, two chip mounting bases on each of which at least one of the semiconductor chips is mounted and a plurality of chip interconnections electrically connected to the terminals of the mounted semiconductor chip are formed into substantially the same pattern and which are stacked in two layers, one interconnection base which is interposed between the two chip mounting bases and on which a plurality of intermediate interconnections electrically connected to the chip interconnections are formed into a pattern different from the pattern of the chip interconnections, and a plurality of interlevel interconnections which are formed in a plurality of through holes extending through the chip mounting bases and the interconnection base at once along a stacking direction and electrically connect the chip interconnections and the intermediate interconnections.